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APPLICATION N	iO.	FILING	GDATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/942,245 08/29/2001		9/2001	Tongbi Jiang	2421.1US (99-0408.1)	8370		
24247	75	90	03/16/2004		EXAMINER		
TRASK BRITT					IM, JUNG	IM, JUNGHWA M	
P.O. BOX 2550 SALT LAKE CITY, UT 84110		84110		ART UNIT	PAPER NUMBER		
0		, 0.			2811		
					DATE MAILED: 03/16/2004	1	

Please find below and/or attached an Office communication concerning this application or proceeding.

			A/
	Application No.	Applicant(s)	r
	09/942,245	JIANG, TONGBI	
Office Action Summary	Examiner	Art Unit	
	Junghwa M. Im	2811	
The MAILING DATE of this communication Period for Reply	appears on the cover sheet w	ith the correspondence address	
A SHORTENED STATUTORY PERIOD FOR RETHE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CF after SIX (6) MONTHS from the mailing date of this communication - If the period for reply specified above is less than thirty (30) days, find the period for reply is specified above, the maximum statutory period for reply within the set or extended period for reply will, by some Any reply received by the Office later than three months after the rearned patent term adjustment. See 37 CFR 1.704(b).	ON. R 1.136(a). In no event, however, may a n. a reply within the statutory minimum of thireriod will apply and will expire SIX (6) MOR tatute, cause the application to become A	reply be timely filed ty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).	
Status			
1) Responsive to communication(s) filed on 1	15 January 2004.		
2a)☐ This action is FINAL . 2b)☒	This action is non-final.		
3) Since this application is in condition for allo closed in accordance with the practice unc	· ·		
Disposition of Claims			
4)	ndrawn from consideration.		
9) The specification is objected to by the Exar	miner		
10) The drawing(s) filed on is/are: a)		by the Examiner	
Applicant may not request that any objection to			
Replacement drawing sheet(s) including the co			
11) The oath or declaration is objected to by the			
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for for a) All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the application from the International But * See the attached detailed Office action for a	nents have been received. nents have been received in A priority documents have beer ireau (PCT Rule 17.2(a)).	Application No received in this National Stage	
Attachment(s)			
 Notice of References Cited (PTO-892) D Notice of Draftsperson's Patent Drawing Review (PTO-948) 		Summary (PTO-413) s)/Mail Date	
Information Disclosure Statement(s) (PTO-1449 or PTO/SI Paper No(s)/Mail Date	· —	Informal Patent Application (PTO-152)	

Application/Control Number: 09/942,245

Art Unit: 2811

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-3, 5-8, 10-12, 14-16, 20, 21, 23, 24, 26-28, 30-33, 35-37, 39-41 and 45-49 are rejected under 35 U.S.C. 102(b) as being anticipated by Yamada et al. (US 5864178), hereinafter Yamada.

Regarding claims 1-3, 6-8, 10-12, 14-16, 20, 21, 23, 24, 26-28, 31-33, 35-37, 39-41 and 45-49, Fig. 58 of Yamada shows a semiconductor assembly comprising:

a semiconductor device (or a die; 201) having an active surface having a plurality of bond pads (224);

a substrate (202) having an upper surface having a plurality of circuits (202; a wiring circuit board);

a plurality of bumps (203) connecting said plurality of bond pads on said active surface of said semiconductor device to said plurality of circuits on said upper surface of said substrate;

said plurality of bumps forming a gap between said semiconductor device and said substrate;

an underfill material (an encapsulation resin; col. 56, lines 20-26) to fill the gap between said substrate and said semiconductor device (or between the substrate and the wetting agent layer);

a wetting agent layer of about a monolayer thick, said wetting agent layer wettable by a polymeric material provided on the active surface of said semiconductor device and on a upper surface of substrate (col. 56, lines 22-63); and

said wetting agent including silane (col. 56, lines 29-63).

Regarding claims 5 and 30, Yamada discloses the wetting agent layer reduces surface tension of the active surface throughout the specification especially in col. 20, lines 34-65.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 4, 9, 13, 19, 22, 29, 34, 38 and 44 are rejected under 35 U.S.C. 103(a) as being unpatentable over Estes in view of Wong et al. (US 6180696), hereinafter Wong.

Regarding claims 4, 9, 13, 19, 22, 29, 34, 38 and 44, Yamada shows a substantially identical structure to the device of the pending claims except a specified wetting material. Wong discloses ethyltrimethoxysilane as a wetting material for an underfill process applied for a flip chip packaging. It would have been obvious to one of ordinary skill in the art at the time of the invention to utilize the teaching of Wong for the wetting layer of Yamada in order to have to good adhesion between chips and substrates, therefore reducing a surface tension in-between as taught in a portion of col. 15, lines 18-22 of Wong's reference.

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Response to Arguments

Applicant's arguments with respect to pending claims have been considered but are moot in view of the new ground(s) of rejection.

In addition, Examiner would like to point out that claim 50 is not pending. Note that claim 50 has never examined with Applicant's consent since the claim limitation is identical to the non-elected claims 17, 18, 25, 42 and 43.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Junghwa M. Im whose telephone number is (571) 272-1655. The examiner can normally be reached on MON.-FRI. 8:30AM-5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C Lee can be reached on (571) 272-1732. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-2197 (toll-free).

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